



3mm One Position CBI Housing

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- RoHS Compliant





Package Schematics

- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

3.5[0.138] 4.96[0.195] Min. 0.3[0.012] 0.04wax.	2.7[0.106]±0.3 6.35[0.25]
2.54[0.1]	5.08[0.2]
	Recommended PCB Layout
Red Yellow	5.08[0.2]
10	2.54[0.1]
1 Anode Red	· · · · · · · · · · · · · · · · · · ·
2 Common Cathode	2.54[0.1]
3 Anode Yellow	
Notes:	$\sqrt{\text{00.9x}}$ 3
1. All dimensions are in millimeters (inches).	

Absolute Maximum Rating (T _A =25°C)	gs	Red (GaAsP/ GaP)	Yellow (GaAsP/ GaP)	Unit
Reverse Voltage	$V_{\rm R}$	5	5	V
Forward Current	I_{F}	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	160	140	mA
Power Dissipation	P_{D}	75	75	mW
Operating Temperature	$T_{\rm A}$	-40 ~	°C	
Storage Temperature	Tstg	-40 ~		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Second			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)	Red (GaAsP/ GaP)	Yellow (GaAsP/ GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	2.1	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	627*	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	617*	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	45	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	20	pF

	Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}20\text{mA}) \ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
					min.	typ.		
	WWW.LIWDOOM	Red	GaAsP/GaP	Mi : D:66 1	12 10*	29 23*	627*	000
XNN1LUYR86M	Yellow	GaAsP/GaP	White Diffused	10 10*	19 19*	590*	60°	

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Oct 06,2016

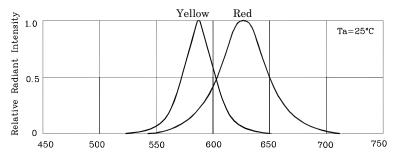
XDSA2766 V8-X Layout: Maggie L.



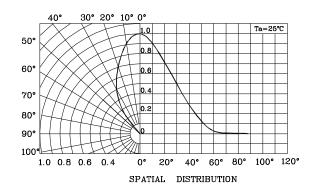


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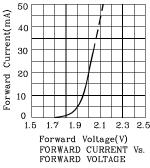


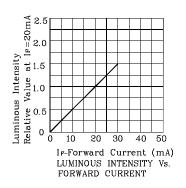


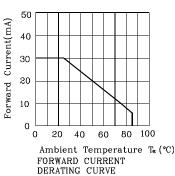
wavelength λ (nm) RELATIVE INTENSITY Vs. CIE WAVELENGTH

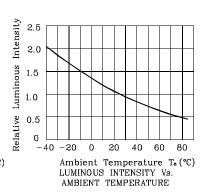


❖ Red

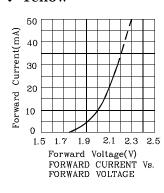


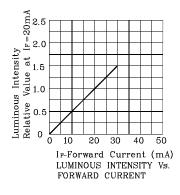


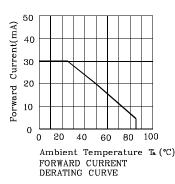


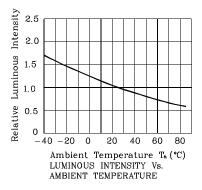


Yellow

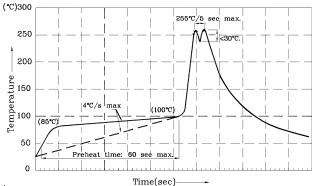








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



- 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec
- (5 sec max).
- (8 sec links).

 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

 4.Fixtures should not incur stress on the component when mounting and during soldering process.

 5.SAC 305 solder alloy is recommended.

 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

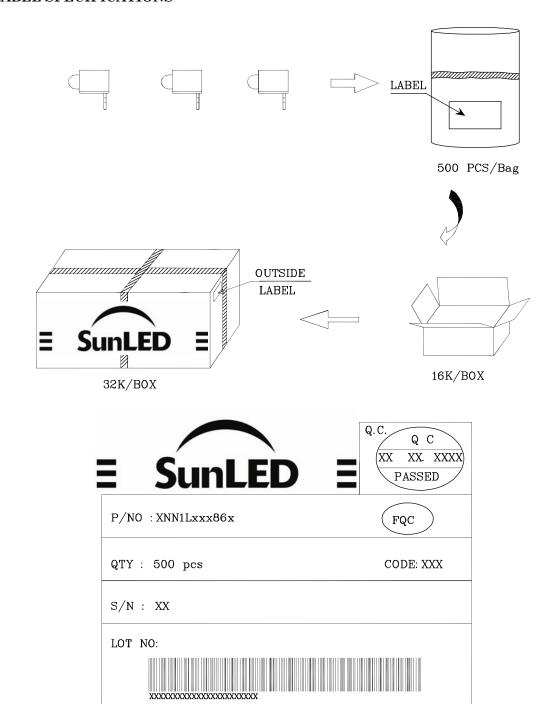
Note: Accuracy may depend on the sorting parameters.

RoHS Compliant





PACKING & LABEL SPECIFICATIONS



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